

## FGW40XS65C

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**Discrete IGBT** 

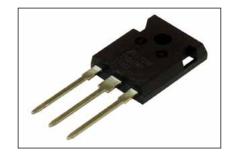
# Discrete IGBT (High-Speed XS-series) 650V / 40A

#### Features

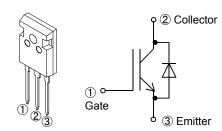
Low power loss Low switching surge and noise High reliability, high ruggedness (RBSOA etc.)

#### Applications

Uninterruptible power supply PV Power coditionner Inverter welding machine



#### Equivalent circuit



TO-247-P2

#### ■ Maximum Ratings and Characteristics

● Absolute Maximum Ratings at T<sub>vi</sub> = 25 °C (unless otherwise specified)

Parameter	Symbol	Value	Unit	Remarks
Collector-Emitter Voltage	<b>V</b> CES	650	V	
Gate-Emitter Voltage	V <sub>GES</sub>	± 20	V	
Transient Gate-Emitter Voltage	<b>V</b> GES	± 30		t <sub>p</sub> < 1 μs
DC Collector Current	Ic@25	61	Α	Tc = 25 °C
DC Collector Current	Ic@100	40	Α	Tc = 100 °C
Pulsed Collector Current	<b>I</b> CP	160	Α	Note *1
Turn-Off Safe Operating Area	-	160	Α	V <sub>CE</sub> ≤ 650 V T <sub>Vj</sub> ≤ 175 °C
Diode Forward Current	I <sub>F@25</sub>	64	Α	
	I <sub>F@100</sub>	40	Α	
Diode Pulsed Current	<b>I</b> FP	160	Α	Note *1
IGBT Max. Power Dissipation	P <sub>tot_IGBT</sub>	234	W	Tc = 25 °C
FWD Max. Power Dissipation	P <sub>tot_FWD</sub>	174	W	T <sub>c</sub> = 25 °C
<b>Operating Junction Temperature</b>	T <sub>vj</sub>	-40 ~ +175	°C	
Storage Temperature	T <sub>stg</sub>	-55 ~ +175	°C	

Note \*1 : Pulse width limited by Tvj max.

● Electrical Characteristics at T₁ = 25 °C (unless otherwise specified)

Parameter	Symbol	Conditions		Min.	Тур.	Max.	Unit
Zero Gate Voltage	/ces		<sub>vj</sub> = 25 °C	-	-	250	μΑ
Collector Current	ICES		<sub>vj</sub> = 175 °C	-	ı	2	mA
Gate-Emitter	/ <sub>GES</sub>	V <sub>CE</sub> = 0 V		_	_	200	nA
Leakage Current	IGES	$V_{GE} = \pm 20 \text{ V}$				200	шА
Gate-Emitter	V <sub>GE(th)</sub>	V <sub>CE</sub> = 20 V		3.4	4.0	4.6	V
Threshold Voltage	V GE(III)	Ic = 40 mA					
Collector-Emitter	.,		vj = 25 °C	1.00	1.35	1.70	
Saturation Voltage	V <sub>CE(sat)</sub>	$I_0 = 40 \text{ A}$	vj = 125 °C	-	1.50	-	V
			<sub>vj</sub> = 175 °C	-	1.60	-	
Input Capacitance	Cies	V <sub>CE</sub> = 25 V		1700	3400	5100	_
Output Capacitance	Coes	$V_{GE} = 0 \text{ V}$		39	78	117	pF
Reverse Transfer Capacitance	Cres	f = 1 MHz		17	34	51	
0-4-01		V <sub>cc</sub> = 520 V		00	400	040	0
Gate Charge	<b>Q</b> <sub>G</sub>	/c = 40 A		80	160	240	nC
Town On Dalay Time	4	V <sub>GE</sub> = 15 V		4.4	20	40	
Turn-On Delay Time Rise Time	t <sub>d(on)</sub>	$T_{vj}$ = 25 °C $V_{cc}$ = 400 V $I_c$ = 20 A $V_{cg}$ = 15 V $I_{cg}$ = 10 Ω		14 8	28 16	42 24	
	-						ns
Turn-Off Delay Time	t <sub>d(off)</sub>			100	200	300	
Fall Time	t <sub>f</sub>			7.5	15	22.5	
Turn-On Energy	Eon	Energy loss include "tail" and FWD reverse recovery.		0.2	0.40	0.60	mJ
Turn-Off Energy	Eoff	- 07	everse recovery.	0.15	0.30	0.45	
Turn-On Delay Time	t <sub>d(on)</sub>			14	28	42	
Rise Time	t <sub>r</sub>	V <sub>cc</sub> = 400 V l <sub>c</sub> = 20 A		11	22	33	ns
Turn-Off Delay Time	t <sub>d(off)</sub>			120	240	360	
Fall Time	t <sub>f</sub>	$V_{\text{GE}} = 15 \text{ V}$		11	22	33	
Turn-On Energy	Eon	$R_G$ = 10 $\Omega$ Energy loss include "tail" and FWD reverse recovery.		0.29	0.58	0.87	mJ
Turn-Off Energy	Eoff		,	0.24	0.48	0.72	.,
- IV // D	.,		v <sub>j</sub> = 25 °C	1.25	1.70	2.15	V
Forward Voltage Drop	<b>V</b> F		vj = 125 °C	-	1.78	-	V
			<sub>vj</sub> = 175 °C	-	1.78	-	V
Diode Reverse Recovery Time	t <sub>rr</sub>	V <sub>cc</sub> = 400 V		42	84	126	ns
D'- 1- D D Ol		$I_F = 20 \text{ A}$		0.45	0.00	4.05	0
Diode Reverse Recovery Charge	Qrr	-di₌/dt = 1200 A/μs T <sub>vi</sub> = 25 °C		0.45	0.90	1.35	μC
Diode Reverse Recovery Time	t <sub>rr</sub>	$V_{cc} = 400 \text{ V}$		63	126	189	no
Diode Reverse Recovery Time	£rr	$V_{\rm F} = 20  \text{A}$		03	120	109	ns
Diode Reverse Recovery Charge	Qrr	-di-dt = 1000 A/us		0.7	1.4	2.1	μC
Dicas iterates iterating	<b></b>	$T_{\rm vi} = 150 ^{\circ}{\rm C}$		0.7			μO

FGW40XS65C

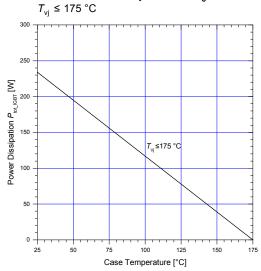
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#### ● Thermal Resistance

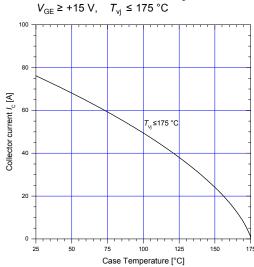
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal Resistance, Junction-Ambient	$R_{th(j-a)}$	-	-	50	°C/W
Thermal Resistance, IGBT Junction to Case	Rth(j-c)_IGBT	-	-	0.642	°C/W
Thermal Resistance, FWD Junction to Case	R <sub>th(j-c)_FWD</sub>	-	-	0.86	°C/W

#### ■ Characteristics (Representative)

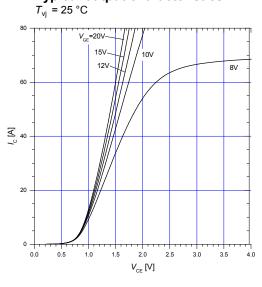
Graph 1 IGBT Power Dissipation vs  $T_c$ 



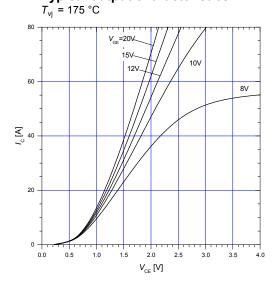
Graph 2 DC Collector Current vs  $T_c$ 



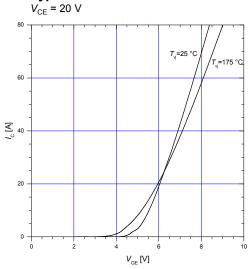
Graph 3
Typical output characteristics



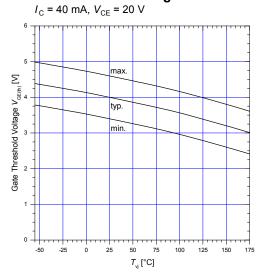
Graph 4
Typical output characteristics



Graph 5
Typical transfer characteristics

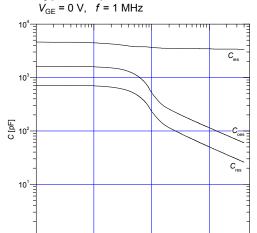


Graph 6
Gate threshold voltage

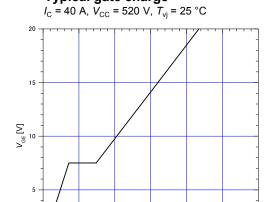


Graph 7
Typical capacitance

10



Graph 8
Typical gate charge

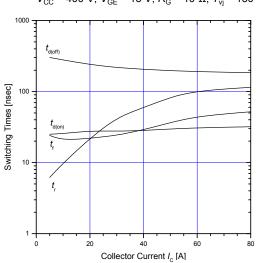


Graph 9 Typical switching times vs.  $I_C$  $V_{CC}$  = 400 V,  $V_{GE}$  = 15 V,  $R_G$  = 10  $\Omega$ ,  $T_{vj}$  = 150 °C

10°

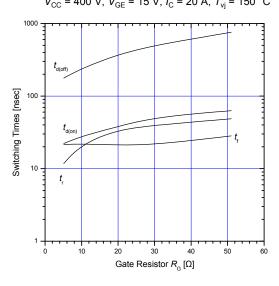
 $V_{\rm CE}$  [V]

10<sup>1</sup>

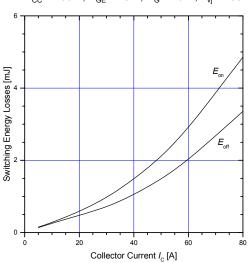


Graph 10 Typical switching times vs.  $R_G$  $V_{CC}$  = 400 V,  $V_{GE}$  = 15 V,  $I_C$  = 20 A,  $T_{Vj}$  = 150 °C

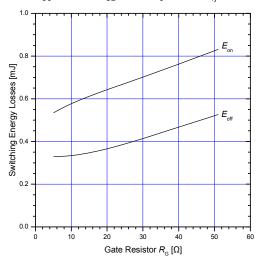
Q<sub>G</sub> [nC]



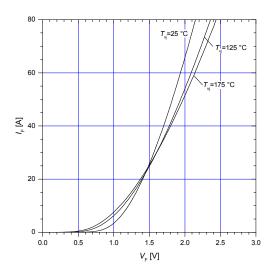
Graph 11 Typical switching losses vs.  $I_c$  $V_{CC}$  = 400 V,  $V_{GE}$  = 15 V,  $R_G$  = 10  $\Omega$ ,  $T_{v_i}$  = 150 °C



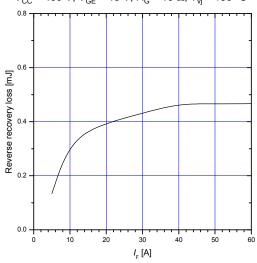
Graph 12 Typical switching losses vs.  $R_G$   $V_{\rm CC}$  = 400 V,  $V_{\rm GE}$  = 15 V,  $I_{\rm C}$  = 20 A,  $T_{\rm vj}$  = 150 °C



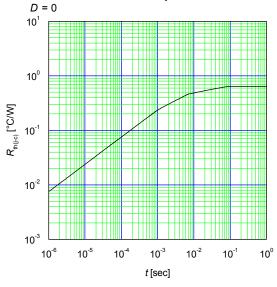
Graph 13
Typical forward characteristics of FWD



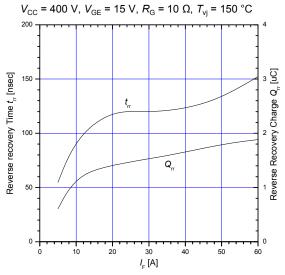
Graph 15 Typical reverse recovery loss vs.  $I_F$  $V_{\rm CC}$  = 400 V,  $V_{\rm GE}$  = 15 V,  $R_{\rm G}$  = 10  $\Omega$ ,  $T_{\rm vj}$  = 150 °C



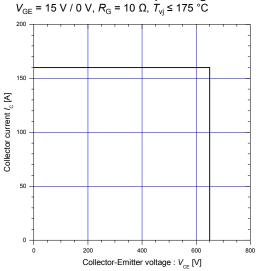
Graph 17 Transient Thermal Impedance of IGBT



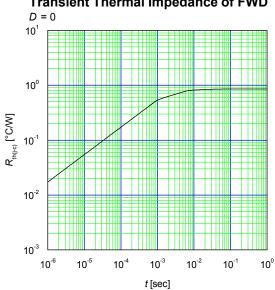
Graph 14 Typical reverse recovery characteristics vs.  $I_F$ 



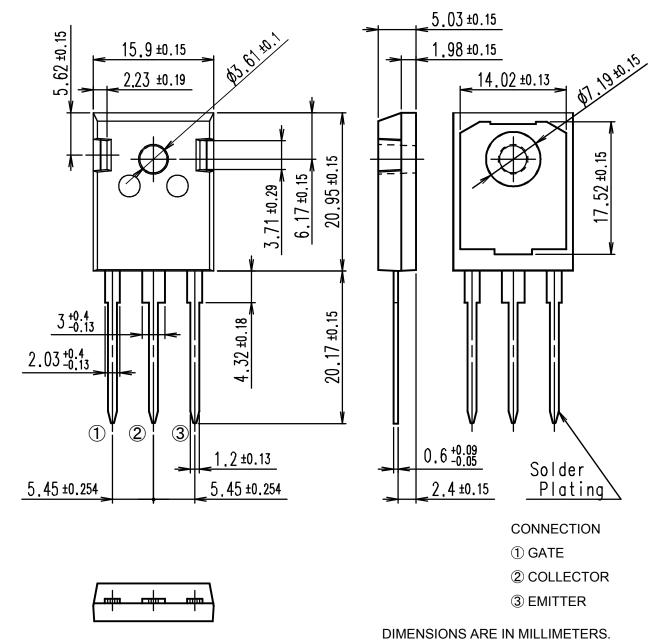
Graph 16
Reverse biased safe operating area



Graph 18
Transient Thermal Impedance of FWD



#### Outline Drawings, mm



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